

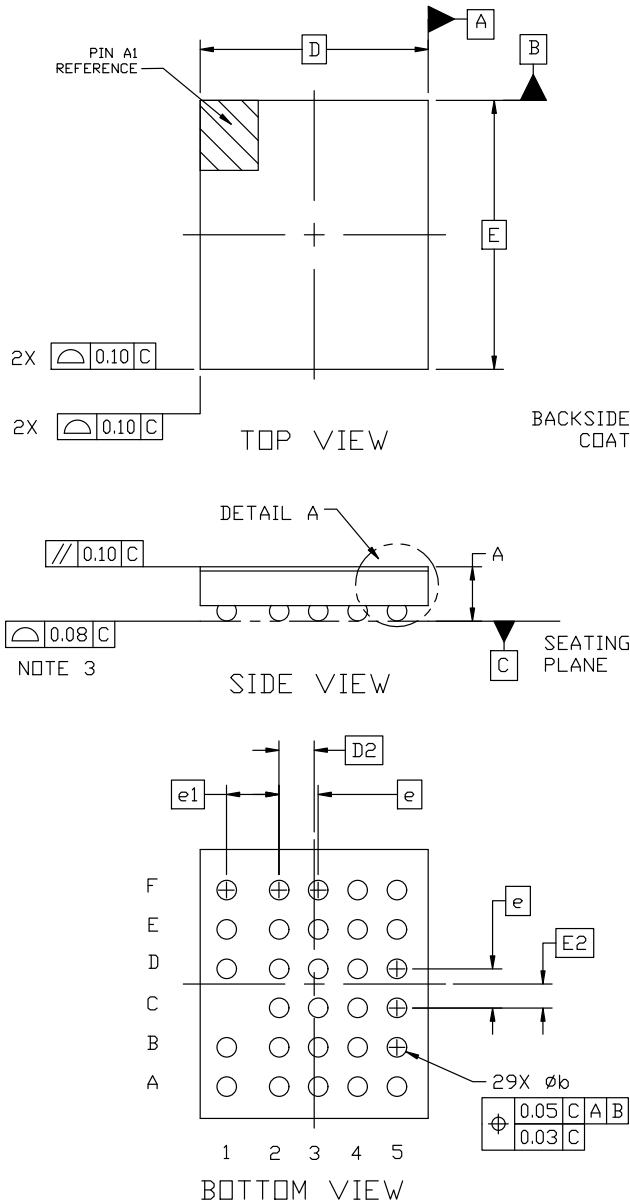
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 4:1

WLCSP29 2.05x1.74x0.417
CASE 567MK
ISSUE A

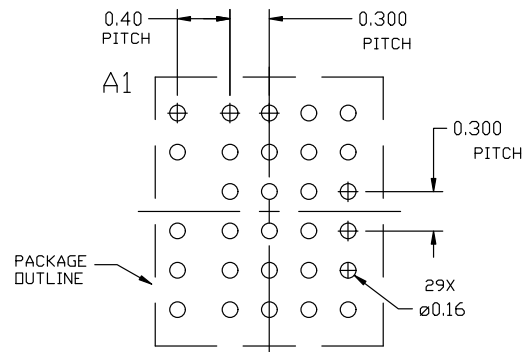
DATE 31 MAY 2023



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.369	0.417	0.465
A1	0.103	0.123	0.143
A2	0.229	0.254	0.279
A3	0.037	0.040	0.043
b	0.137	0.157	0.177
D	1.740 BSC		
D2	0.270 BSC		
E	2.050 BSC		
E2	0.185 BSC		
e	0.300 BSC		
$e1$	0.400 BSC		



RECOMMENDED
MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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